

Investigation of high resistivity p-type FZ silicon diodes after ^{60}Co - γ irradiation



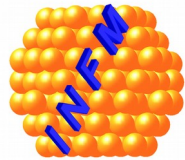
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Particle or Gamma-ray (Compton effect 1MeV electron)

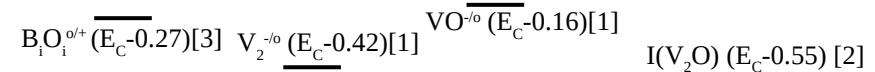
Previous work (presented on RD50 workshop):

Type of Radiation

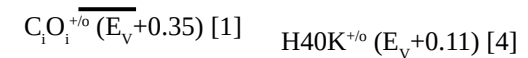
- 23 GeV Protons ($4.3 \times 10^{13} n_{eq}/cm^2$, $N_{eff} = 10^{12} \sim 10^{15} cm^{-3}$ – **Doping dependent**): Comparing the decreases of N_{eff} with defect formation; Current related damage parameter α (Hamburg model, cluster related defect); Annealing behavior
- 6 MeV electrons ($10^{13} \sim 10^{14} n_{eq}/cm^2$ – **Fluence dependent**, $N_{eff} = 10^{15} cm^{-3}$): N_{eff} , α and annealing behavior comparing with proton irradiation; Comparing the Cz ($[C] \approx 2 \times 10^{15} cm^{-3}$) and EPI ($[C] \approx 3 \times 10^{16} cm^{-3}$) diodes
- **$^{60}Co - \gamma$?**

The observed results from both literature and our works (depend on initial doping, type of radiation and fluence):

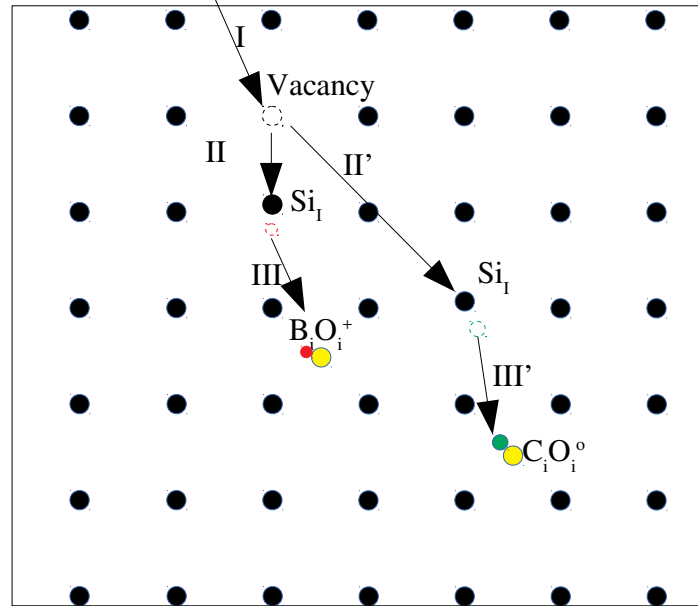
Conduction _____



Half of band gap -----



Valence _____



Schematic of radiation damage in p-type silicon sensor

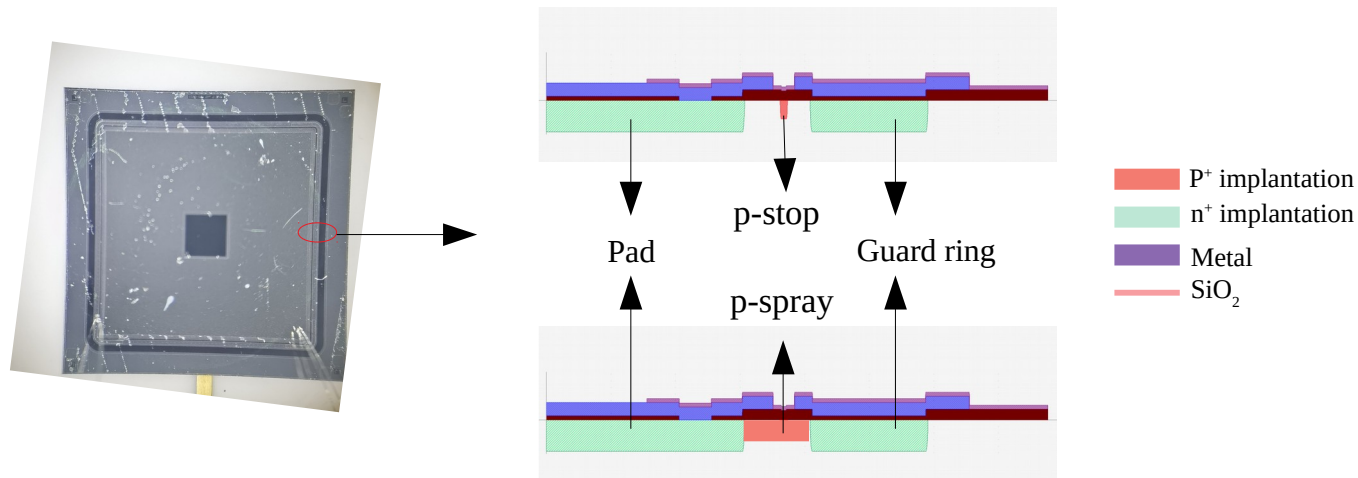
I: Lattice Silicon atom (Si_s) was knocked out by incident particle and Si_s got recoil energy and turns to interstitial silicon (Si_i)

II: Si_i diffusion in the bulk and impact on Lattice Boron atom (B_s)

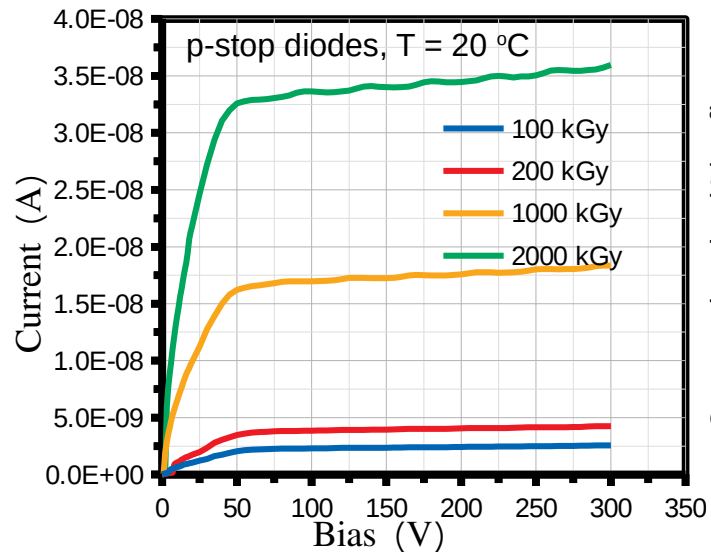
III: B_s was knocked out Si_i and turns to interstitial Boron (B_i) and finally captured by interstitial Oxygen (O_i)

Details of samples investigated (high resistivity $\sim 3 \text{ k}\Omega\text{cm}$ p-type FZ material from Hamamatsu)

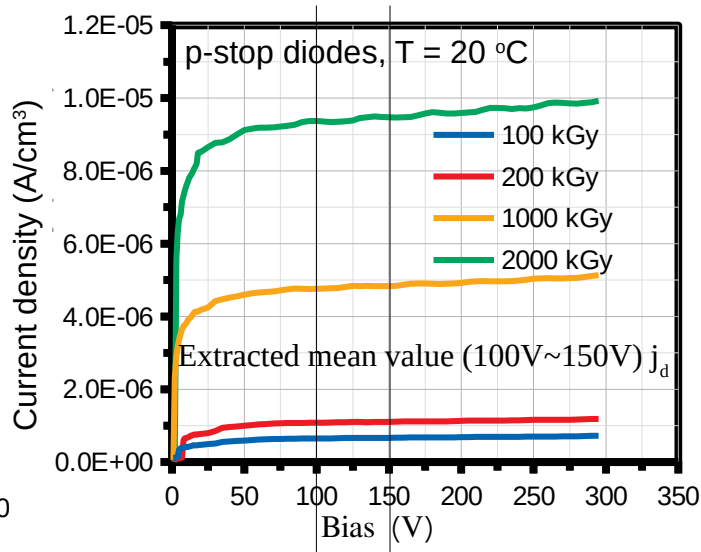
Initial doping, bulk (cm^{-3})	$\sim 3.5 \times 10^{12}$			
^{60}Co - γ irradiation (kGy)	100(94 ± 0.96)	200(189 ± 3.9)	1000(924 ± 27)	2000(1860 ± 56)
Area (cm^2)	0.25			
Thickness (μm)	150			



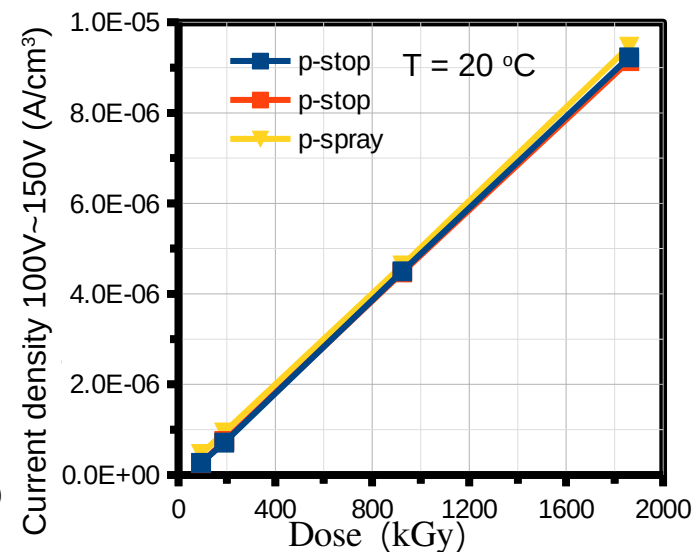
I-V measurements

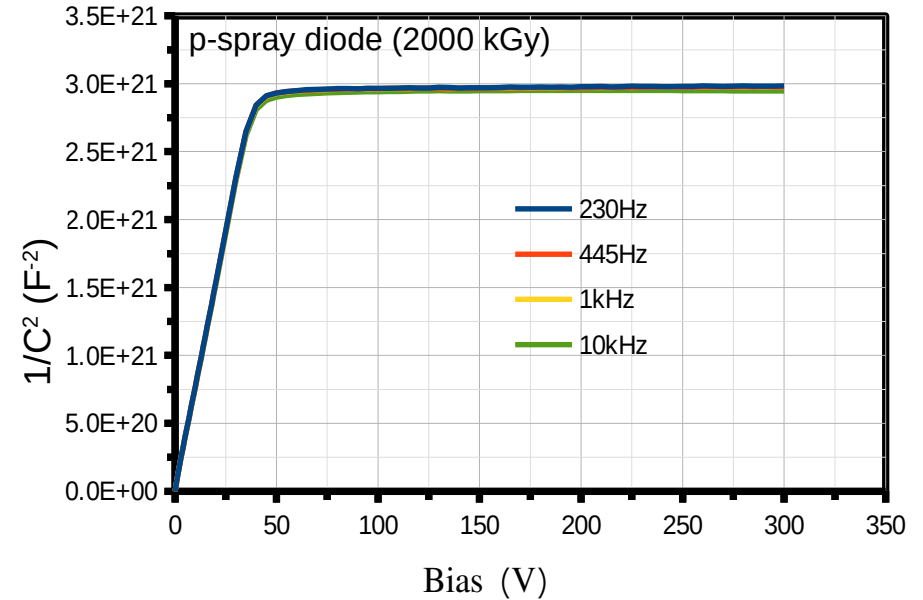
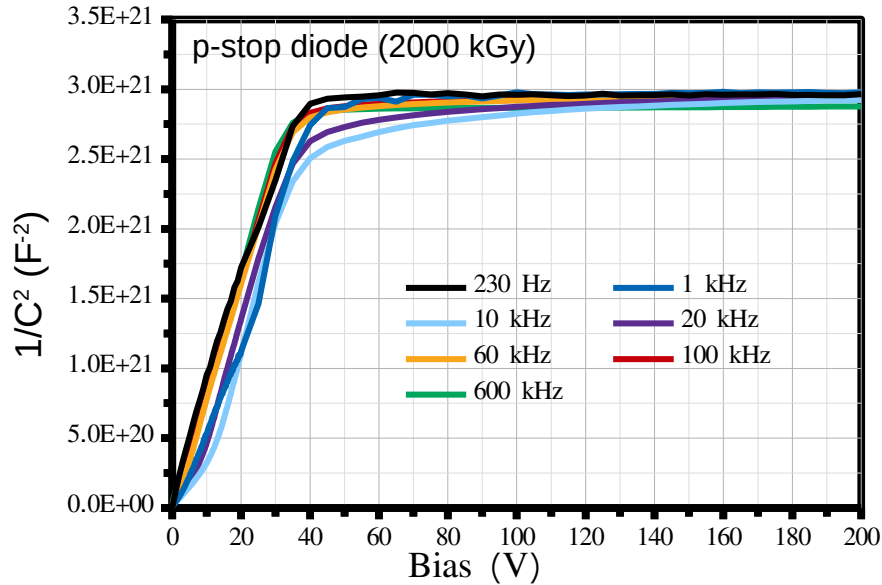


I-V measurements

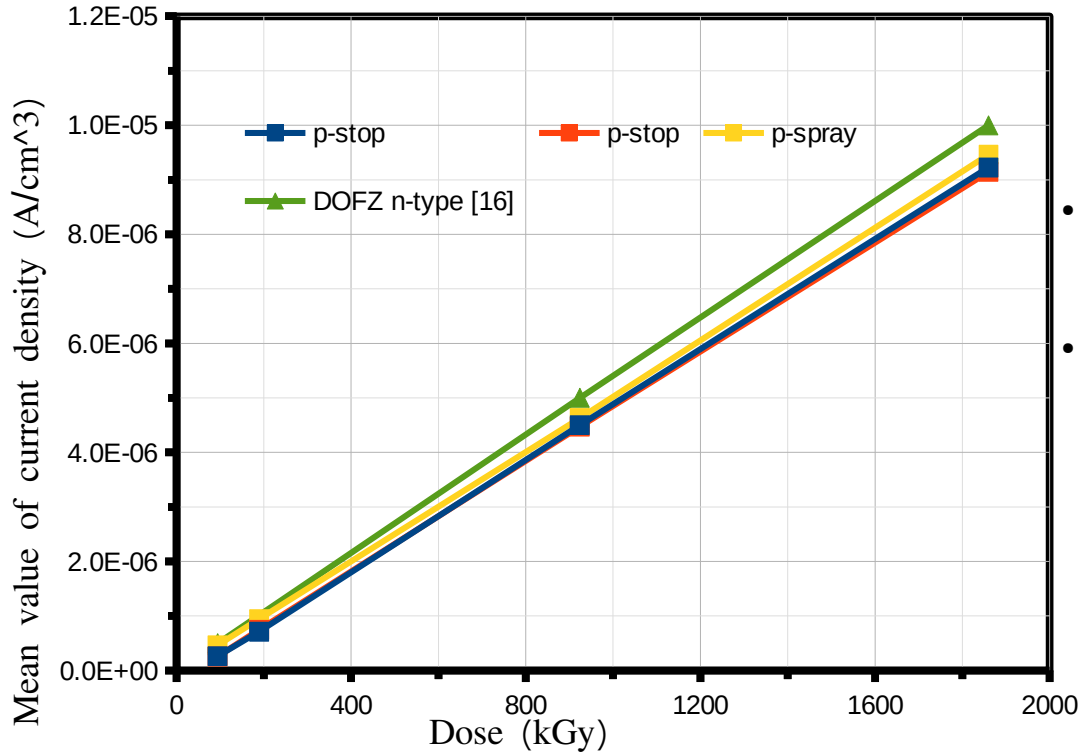


100 V 150 V
 Current density given by I-V and C-V (100 kHz for p-stop diodes)



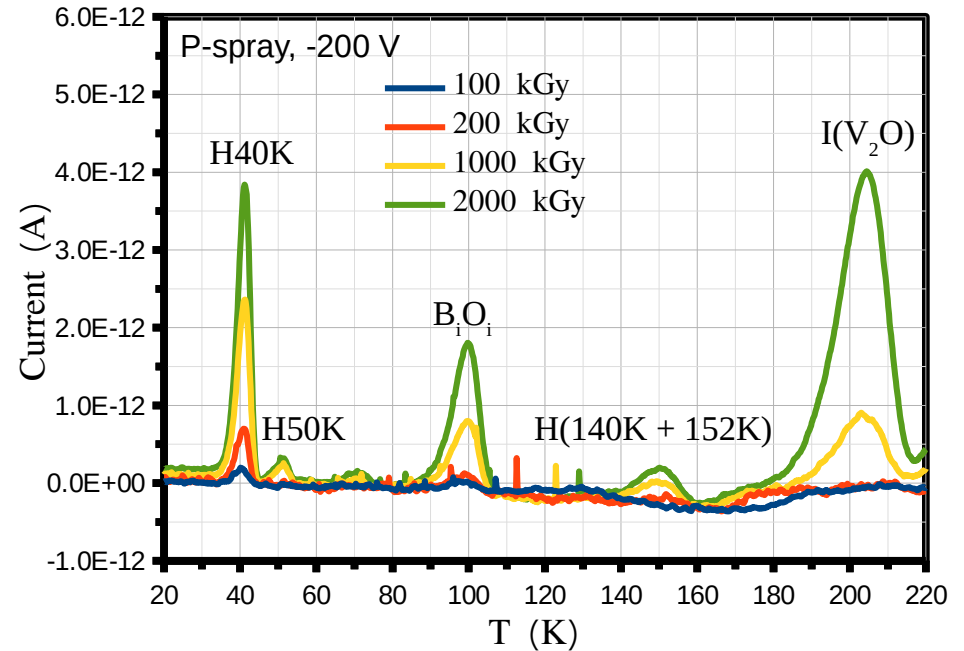
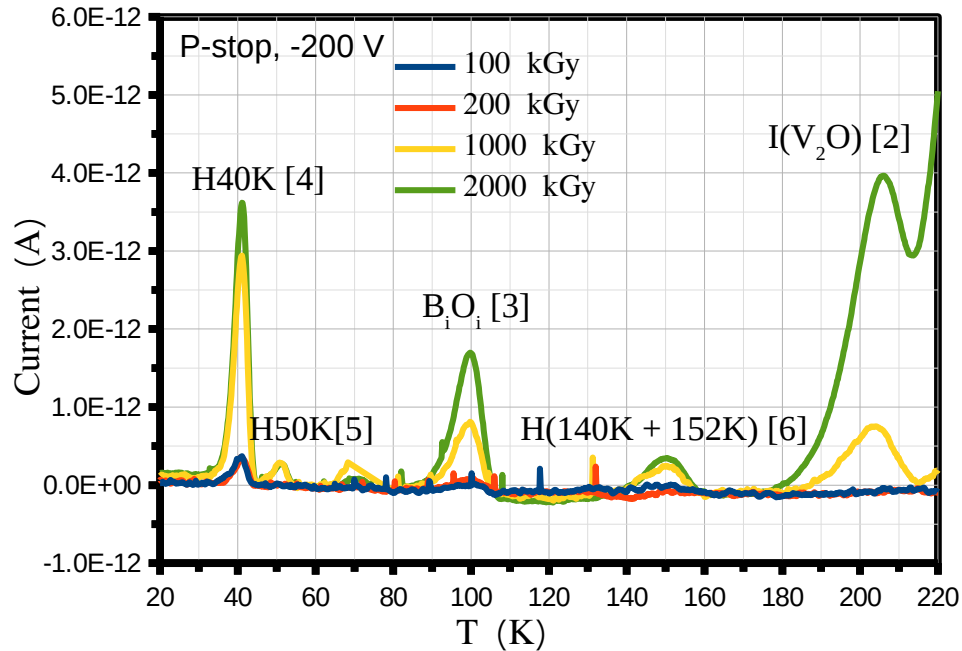


- C-V measurement for p-stop diode (left, 2000 kGy, freq = 230Hz ~ 600 kHz) and p-spray diode (right, 2000 kGy, freq = 230Hz ~ 10 kHz)
- Measured at room temperature, $V_{AC} = 0.5$ V
- Observation:
 - No frequency dependence for p-spray diode
 - Frequency dependence for p-stop diode

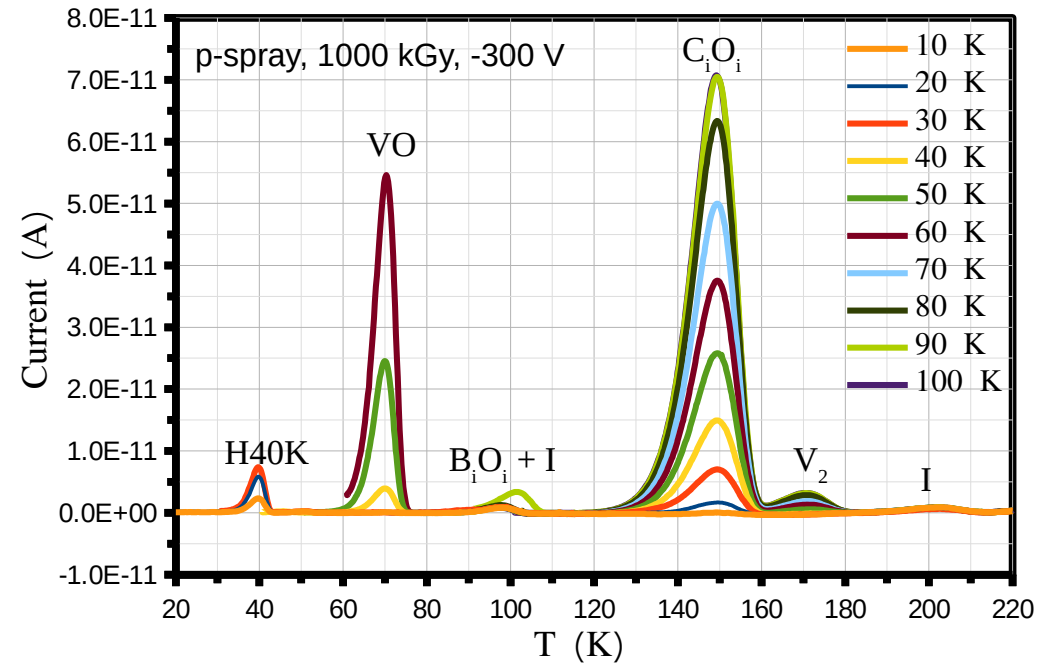
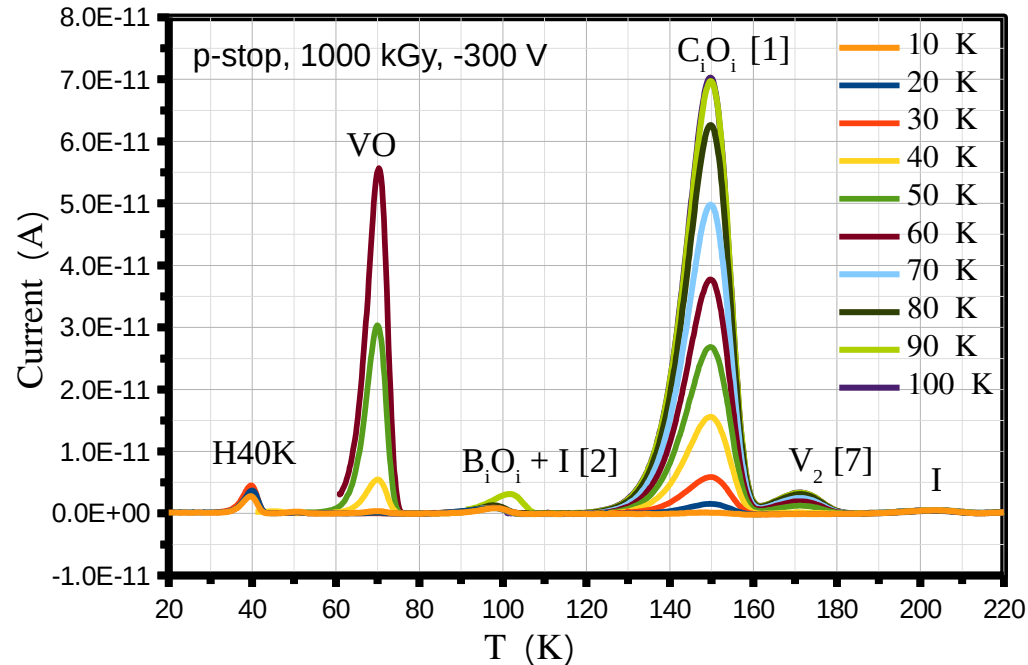


- The estimated value of leakage current density of n-type was included (DOFZ – Oxygen enriched diodes. $[O] \approx 1 \times 10^{17} \text{ cm}^{-3}$).
- Similar behavior on development of j_d with dose value, possibly due to both are oxygen-enriched (10^{17} cm^{-3}) [2] compare to standard FZ (Standard FZ $[O] = 5 \times 10^{15} \text{ cm}^{-3}$) [2]

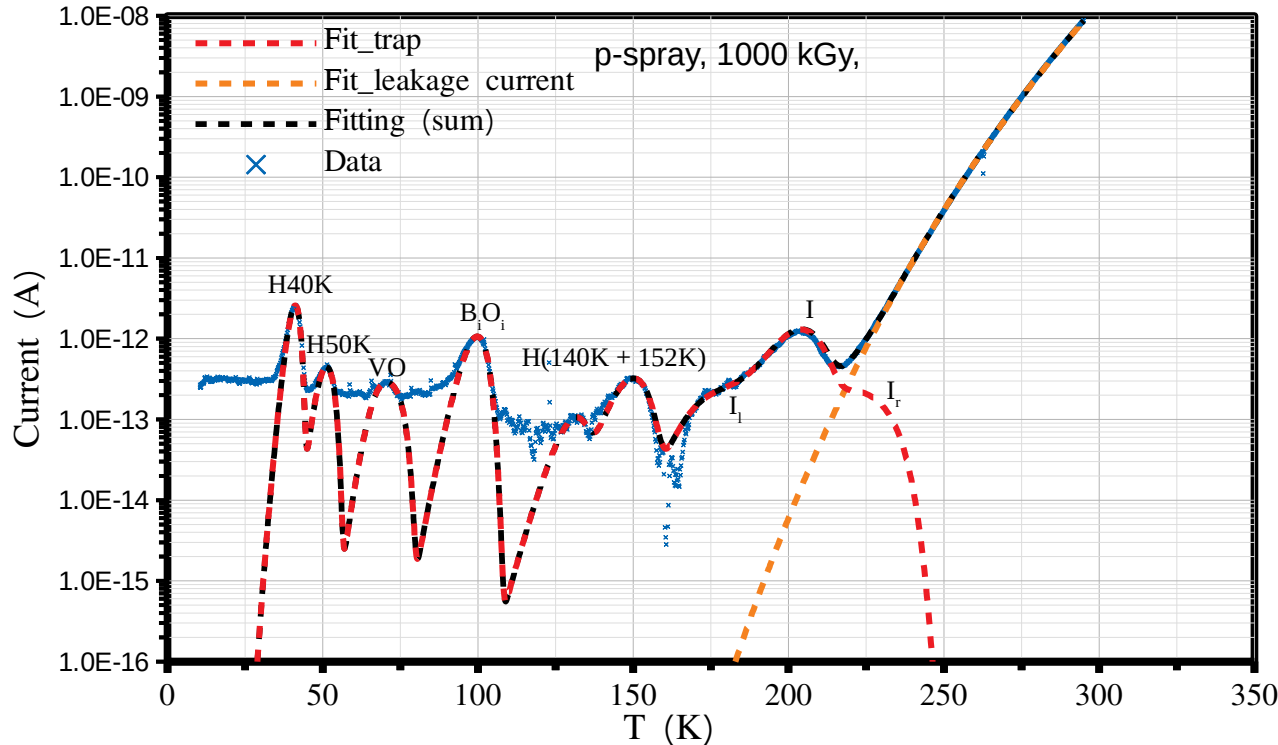
TSC measurement (-200 V)



- Forward bias filling, filling current $I_{\text{fill}} = 0.8$ mA, filling temperature at $T_{\text{fill}} = 10$ K for 30 s, heating rate $\beta = 0.183$ K/s and $V_{\text{heat up}} = -200$ V



- p-stop diode, 1000 kGy (left) / p-spray diode, 1000 kGy (right)
- Same experimental parameters as presented before, except for $V_{\text{heat up}} = -300$ V and T_{fill}
- The amplitude of H40K, VO, C_iO_i and V_2 appeared strongly dependent on T_{fill}



Peak fitting example of TSC spectra (1000 kGy, p-spray diode, $T_{fill} = 10K$, $V_{heat-up} = -200V$)

Fit_trap[8-12]:

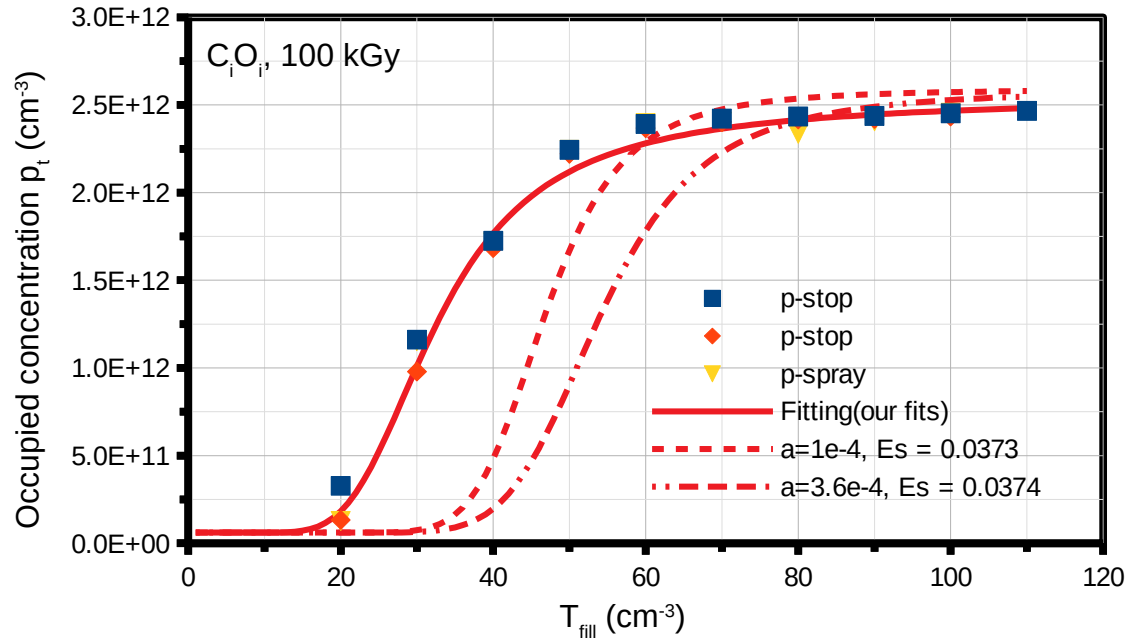
$$I_{isc} = \frac{1}{2} q_0 A d N_t e_n \exp\left(-\frac{1}{\beta} \int e_n(T) dT\right)$$

Three free parameters: The defect concentration N_t with two factors implanted into emission rate e_n – the capture cross section σ and activation energy E_a .

Fit_leakage current (high temperature range):

$$I_{LC} = C \cdot T^n \cdot \exp\left(-\frac{\delta E}{k_B T}\right)$$

Three free parameters: C ; n (1~3); δE (~0.73, voltage dependent – Poole Frenkel and tunneling).



Such fitting procedures only work for lower dose values ($\sim 100 \text{ kGy}$ and $\sim 200 \text{ kGy}$) and only for $C_i O_i$

Conclusion: determine the concentration in saturation
 – Details on the next slides

Occupied state during filling can be estimated by:

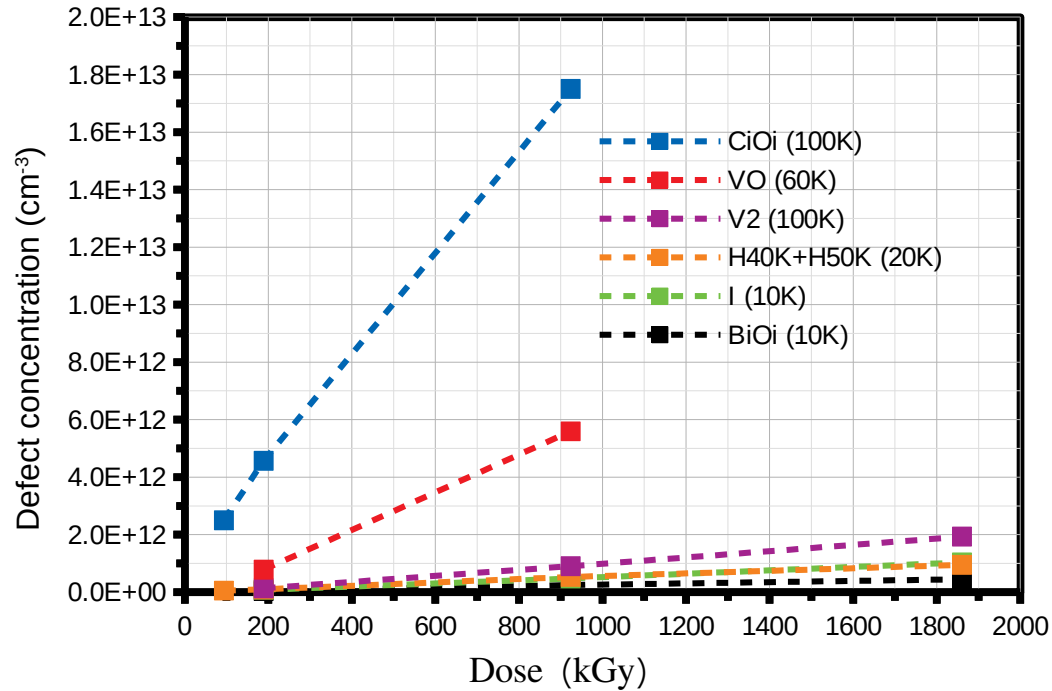
$$n_t = N_t \times \frac{1}{1 + \frac{c_p(T) \cdot p}{c_n(T) \cdot n}} \quad \text{or} \quad p_t = N_t \times \frac{1}{1 + \frac{c_n(T) \cdot n}{c_p(T) \cdot p}}$$

Forward bias filling $n \approx p$, the occupation was determined by the ratio between C_p and C_n .

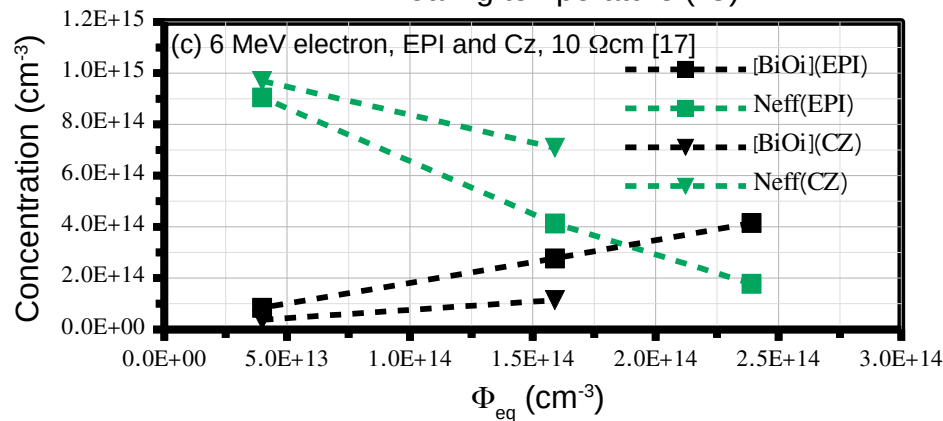
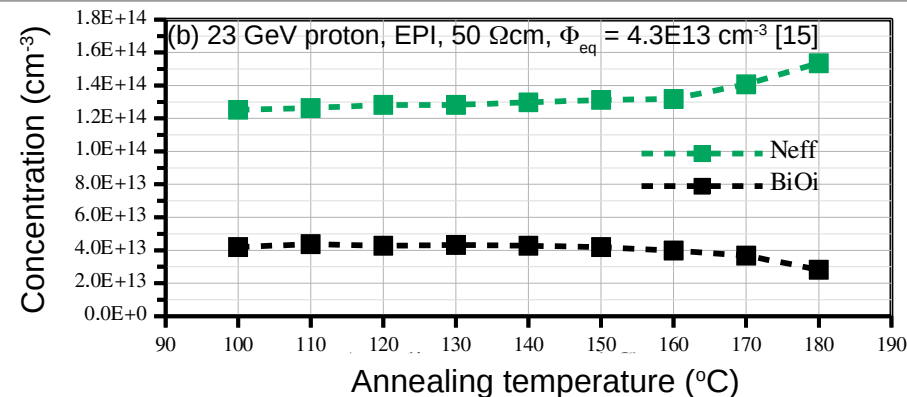
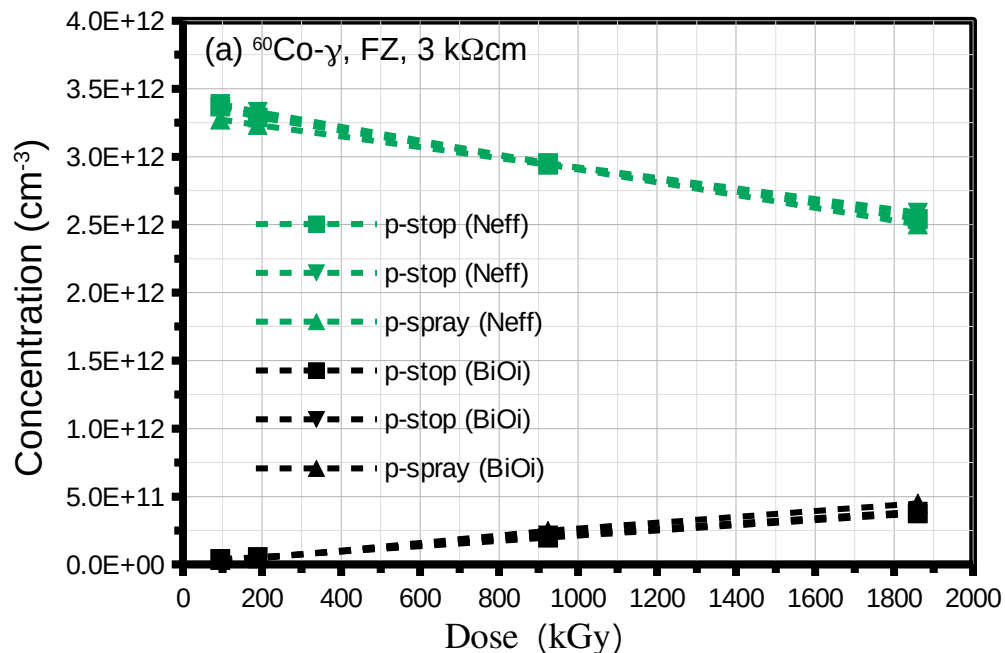
Filling function given by multi-phonon captured[13]:

$$p_t = N_{\text{offset}} + N_t \times \frac{1}{1 + a \cdot \exp\left(\frac{E_s}{k_B T_{\text{fill}}}\right)}$$

	Our fits	Reference value (neutron)
N_{offset} (cm^{-3})	6.061×10^{10}	
N_t (cm^{-3})	2.531×10^{12}	
a	0.0118	$1\text{e-}4$ [1] or $3.4\text{e-}4$ [14]
E_s (eV)	0.013	0.0373 [1] or 0.0374 [14]



- The first formation of trap is C_iO_i , H40K+H50K (Possibly vacancy related) and B_iO_i (or X-defect [15]?)
- The concentration of C_iO_i should be proved by further experiments e.g electron or hole injection



- Development of B_iO_i concentration and N_{eff} with dose value (a), annealing temperature (b) and NIEL fluence transferred by 6 MeV electron (c)
- The decrease of Neff given by CV measurement
- ΔNeff ≈ 2×Δ[B_iO_i] (for all figure presented in this slide)

I. Results for FZ p-type diodes irradiated by ^{60}Co γ with dose value (100 kGy, 200 kGy, 1000 kGy and 2000 kGy):

a). Macroscopic measurement (I-V, C-V):

- j_d linear increasing with dose value
- Frequency-dependent of C-V didn't appear on p-spray diodes

b). Microscopic measurement (TSC):

- T_{fill} dependence of amplitude was observed on the defects (H40K , VO , C_iO_i and V_2) and analyzed with multi-phonon captivation
- The development of defect concentration with dose value
- $\Delta N_{\text{eff}} \approx 2 \times \Delta[\text{B}_i\text{O}_i]$

II. Comparison with n-type materials:

- Current density increase with fluence is the same for p-type and n-type

Further plans :

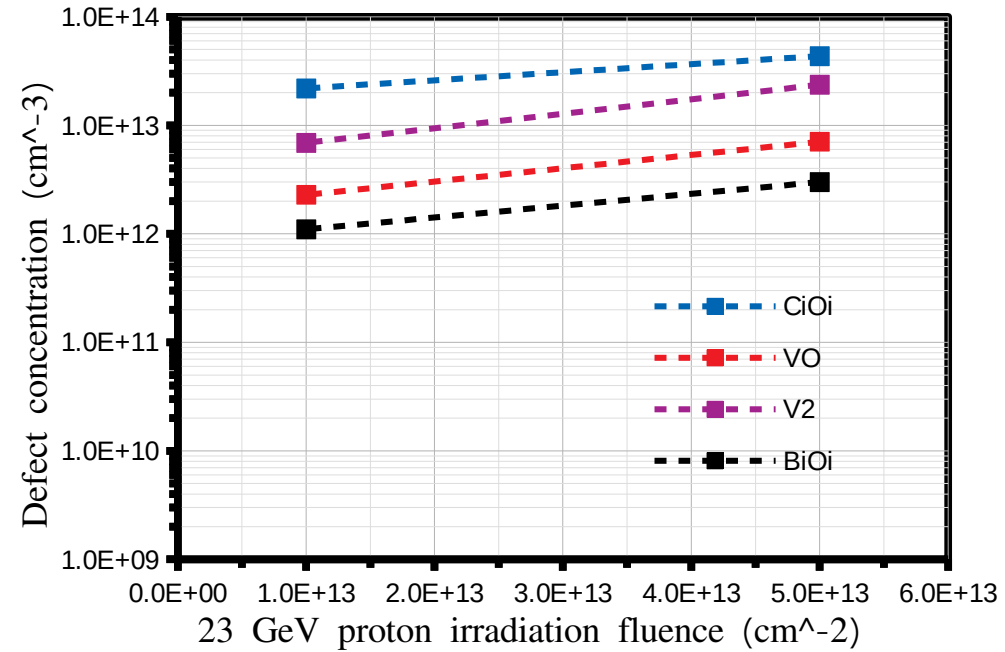
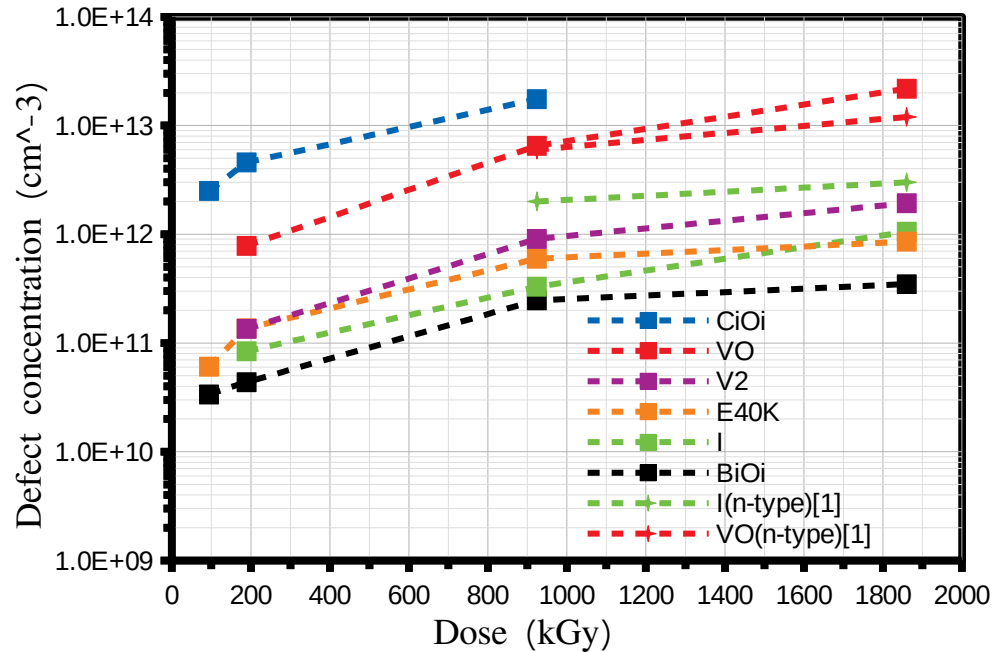
1. annealing behavior
2. identified surface traps



Back up

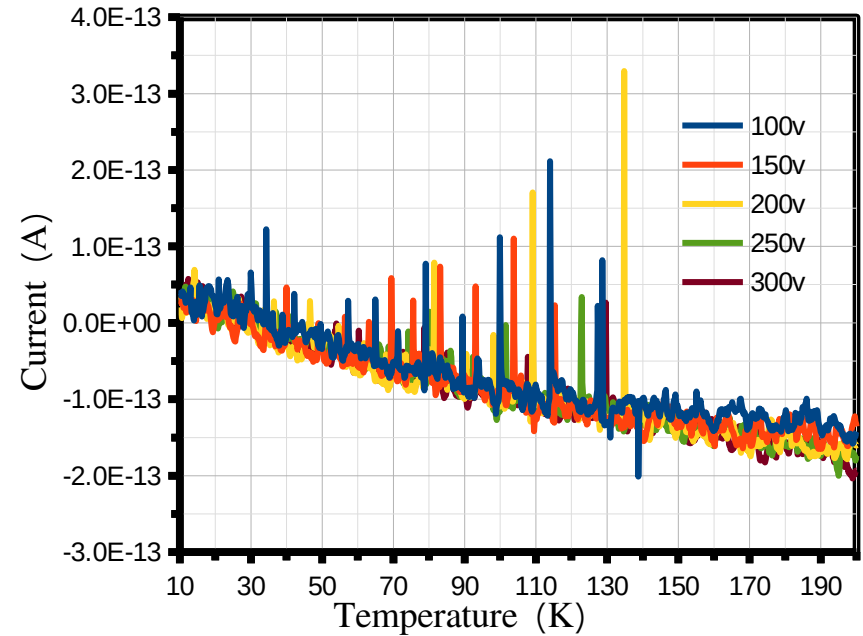
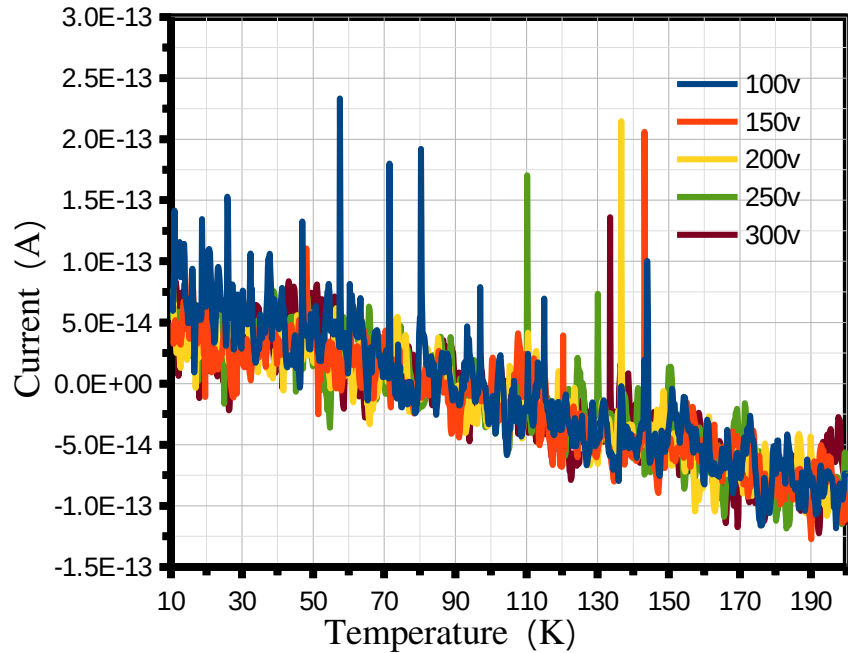
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Compare with other materials (defect)

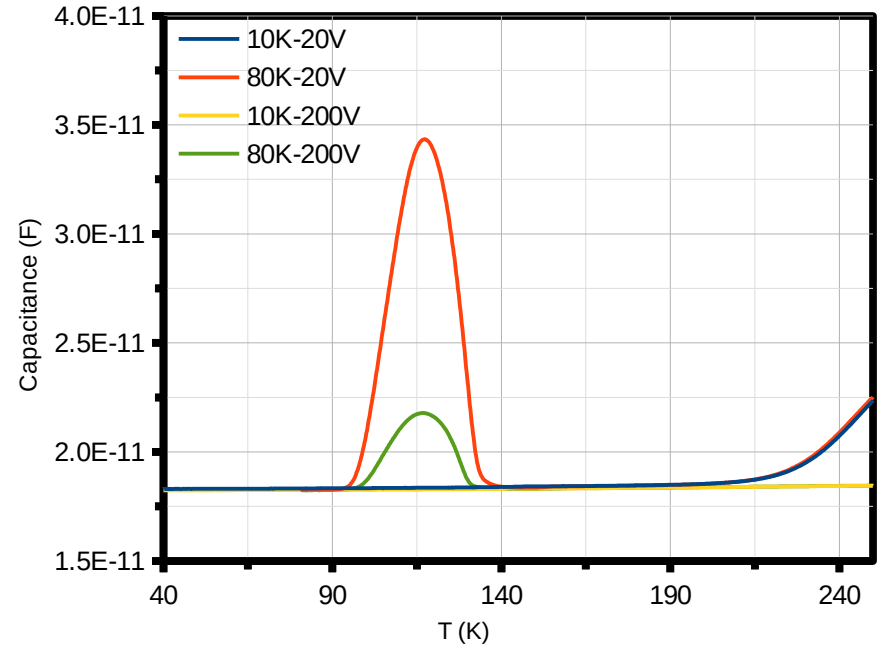
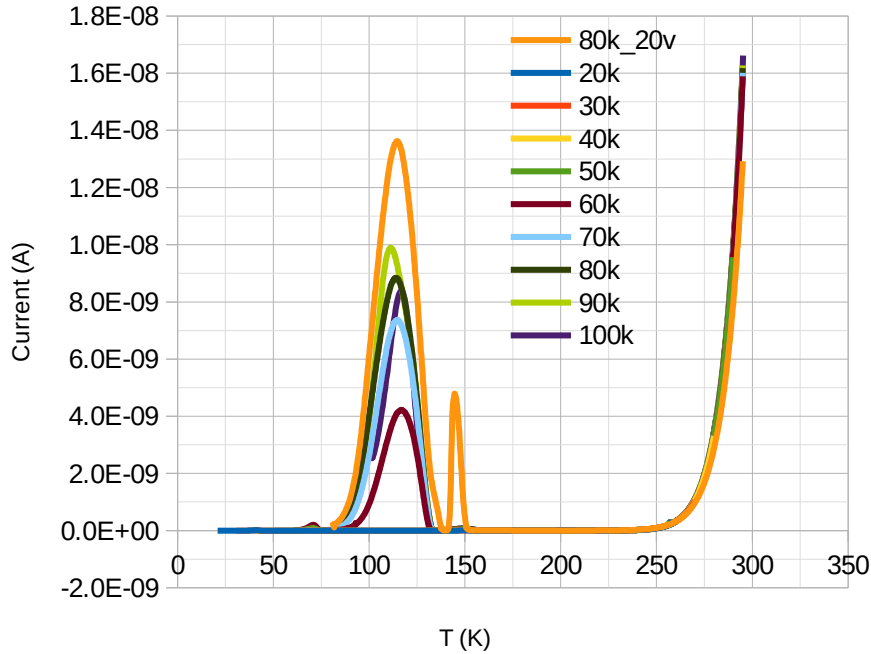


- Defect concentration extracted from TSC for different material and particle irradiation. (left) the n-type also is FZ sample
- I (possibly VO₂) higher and VO lower on n-type diodes than to p-type for 100 Mrad and 200 Mrad irradiation
- V₂ concentration higher than VO for proton irradiation

Noise



Strange peak



I-V for proton irradiation

